

PCN Number:	20150318000		PCN Date:	03/20/2015	
Title:	Qualification of GFAB as an additional Wafer Fab site option for select devices in ABCD05/ABCD5HV Technology				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	06/20/2015	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of GFAB as an additional Wafer Fab site option for the products listed in the product affected section of this document.

Current Wafer Fab Site	Process	Wafer Diameter
MAINEFAB	ABCD05/ABCD5HV	200mm

Additional Fab Site	Process	Wafer Diameter
GFAB8	ABCD05/ABCD5HV	200mm

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
MAINEFAB	CUA	USA

New

Chip Site	Chip site code (20L)	Chip country code (21L)
GFAB8	GF8	GBR

Sample product shipping label (not actual product label)

 <p>MADE IN: Malaysia 2DC: 20:</p> <table border="1" style="font-size: small;"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 LBL: 5A (L)T0:1750</p>	MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04	 G4 	<p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV. (V) 0033317 (20L) CS0: SHE (21L) CCO: USA (22L) AS0: MLA (23L) ACC: MYS</p>
MSL 2 / 260C / 1 YEAR	SEAL DT					
MSL 1 / 235C / UNLIM	03/29/04					

Product Affected:

LM25017DDA	LM25018SDE/NOPB	LM34937PSQ/NOPB	LM5056APMH/NOPB
LM25017DDAR	LM25018SDX/NOPB	LM34937PSQX/NOPB	LM5056APMHE/NOPB
LM25017MR/NOPB	LM25117PMH/NOPB	LM5017MR/NOPB	LM5056APMHX/NOPB
LM25017MRE/NOPB	LM25117PMHE/NOPB	LM5017MRE/NOPB	LM5056PMH/NOPB
LM25017MRX/NOPB	LM25117PMHX/NOPB	LM5017MRX/NOPB	LM5056PMHE/NOPB
LM25017NGU	LM25117PSQ/NOPB	LM5017SD/NOPB	LM5056PMHX/NOPB
LM25017NGUR	LM25117PSQE/NOPB	LM5017SDE/NOPB	LM5066PMH/NOPB
LM25017NGUT	LM25117PSQX/NOPB	LM5017SDX/NOPB	LM5066PMHE/NOPB
LM25017SD/NOPB	LM3481MM/NOPB	LM5018MR/NOPB	LM5066PMHX/NOPB
LM25017SDE/NOPB	LM3481MMX/NOPB	LM5018MRX/NOPB	LM5066UPMH/NOPB
LM25017SDX/NOPB	LM34926MR/NOPB	LM5018SD/NOPB	LM5066UPMHE/NOPB
LM25018DDA	LM34926MRX/NOPB	LM5018SDX/NOPB	LM5066UPMHX/NOPB
LM25018DDAR	LM34926SD/NOPB	LM5046DAP	TPS92411DBVR
LM25018DDAT	LM34926SDX/NOPB	LM5046DAPR	TPS92411DBVT
LM25018MR/NOPB	LM34927MH/NOPB	LM5046DAPT	TPS92411DDA
LM25018MRE/NOPB	LM34927MR/NOPB	LM5046MH/DRSN	TPS92411DDAR
LM25018MRX/NOPB	LM34927MRX/NOPB	LM5046MH/NOPB	TPS92411PDBVR
LM25018NGU	LM34927SD/NOPB	LM5046MHX/CY	TPS92411PDBVT
LM25018NGUR	LM34927SDX/NOPB	LM5046MHX/NOPB	TPS92411PDDA
LM25018NGUT	LM34937PMH/NOPB	LM5046SQ/NOPB	TPS92411PDDAR
LM25018SD/NOPB	LM34937PMHX/NOPB	LM5046SQX/NOPB	

**Qualification of ABCD5HV process in GFAB, Scotland
Approved 8/29/2014**

Attributes	Qual Device: LM5006MM/NOPB
Wafer Fab Supplier	GFAB
Wafer Diameter	200mm
Wafer Fab Process	ABCD5HV

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM5006MM/NOPB
PC	Preconditioning Level 1	Level 1-260C	3/743/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
AC	Autoclave 121C	96 Hours	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/50/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
ELFR	Early Life Failure Rate, 125C	48 Hours	3/2400/0
HBM	ESD - HBM - Q100	2000 V	3/9/0
CDM	ESD - CDM - Q100	250 V	3/9/0
LU	Latch-up	(Per JESD78)	3/18/0

- Qual Device LM5006MM/NOPB is qualified at LEVEL1-260C
- Preconditioning was performed for Biased HAST, AC, HTSL and Temperature Cycle as applicable.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

**Qualification of ABCD5 Process in GFAB, Scotland
Approved 02/13/2015**

Attributes	Qual Device: LM22679QTJ-ADJ
Wafer Fab Site	GFAB
Wafer Diameter	200mm
Wafer Fab Process	ABCD5

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM22679QTJ-ADJ
PC	Preconditioning Level 1	Level 1-260C	3/308/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
HTSL	High Temp Storage Bake, 150C	1000 Hours	1/77/0
HTOL	Life Test, 150C	500 Hours	3/231/0
ELFR	Early Life Failure Rate, 125C	48 Hours	3/1358/0
ELFR	Early Life Failure Rate, 150C	48 Hours	3/716/0
HBM	ESD - HBM	1000 V	3/9/0
CDM	ESD - CDM	1000 V	3/9/0
LU	Latch-up	(Per JESD78)	3/18/0

- Qual Device LM22679QTJ-ADJ is qualified at LEVEL1-260C
- Preconditioning was performed for Temperature Cycle and HTSL as applicable

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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